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INTEGRATED CIRCUITS

DATA SHEET

TDA7056B5 W mono BTL audio amplifier with DC volume control

Product specification Supersedes data of 1996 May 28



5 W mono BTL audio amplifier with DC volume control

TDA7056B

FEATURES

- DC volume control
- · Few external components
- Mute mode
- Thermal protection
- · Short-circuit proof
- · No switch-on and switch-off clicks
- · Good overall stability
- Low power consumption
- Low HF radiation
- ESD protected on all pins.

GENERAL DESCRIPTION

The TDA7056B is a mono Bridge-Tied Load (BTL) output amplifier with DC volume control.

It is designed for use in TV and monitors, but is also suitable for battery-fed portable recorders and radios. The device is contained in a 9-pin medium power package.

A Missing Current Limiter (MCL) is built in. The MCL circuit is activated when the difference in current between the output terminal of each amplifier exceeds 100 mA (300 mA typ.). This level of 100 mA allows for headphone applications (single-ended).

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage		4.5	_	18	V
Po	output power	V _P = 12 V				
		$R_L = 16 \Omega$	3	3.5	_	W
		$R_L = 8 \Omega$	5	5.5	_	W
G _{v(max)}	maximum total voltage gain		39.5	40.5	41.5	dB
ф	gain control		68	73.5	_	dB
I _{q(tot)}	total quiescent current	$V_P = 12 \text{ V}; R_L = \infty$	_	9.2	13	mA
THD	total harmonic distortion	P _O = 0.5 W	_	0.3	1	%

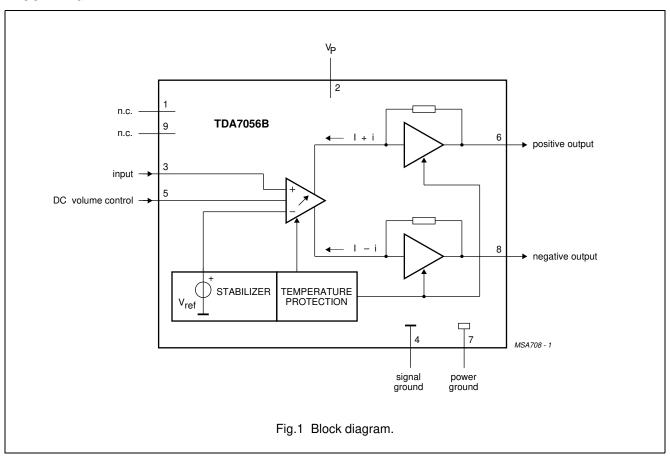
ORDERING INFORMATION

TYPE		PACKAGE					
NUMBER	NAME	DESCRIPTION	VERSION				
TDA7056B	SIL9MPF	plastic single in-line medium power package with fin; 9 leads	SOT110-1				

5 W mono BTL audio amplifier with DC volume control

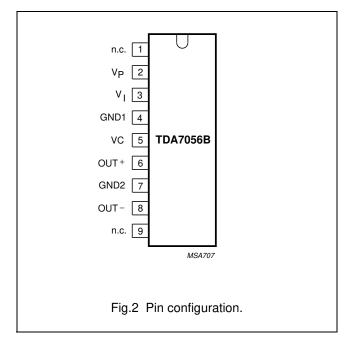
TDA7056B

BLOCK DIAGRAM



PINNING

SYMBOL	PIN	DESCRIPTION			
n.c.	1	not connected			
V_P	2	positive supply voltage			
VI	3	voltage input			
GND1	4	signal ground			
VC	5	DC volume control			
OUT+	6	positive output			
GND2	7	power ground			
OUT-	8	negative output			
n.c.	9	not connected			



5 W mono BTL audio amplifier with DC volume control

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FUNCTIONAL DESCRIPTION

The TDA7056B is a mono BTL output amplifier with DC volume control, designed for use in TV and monitor but is also suitable for battery-fed portable recorders and radios.

In conventional DC volume circuits the control or input stage is AC coupled to the output stage via external capacitors to keep the offset voltage low. In the TDA7056B the DC volume control stage is integrated into the input stage so that no coupling capacitors are required. With this configuration, a low offset voltage is still maintained and the minimum supply voltage remains low.

The BTL principle offers the following advantages:

- Lower peak value of the supply current
- The frequency of the ripple on the supply voltage is twice the signal frequency.

Consequently, a reduced power supply with smaller capacitors can be used which results in cost reductions. For portable applications there is a trend to decrease the supply voltage, resulting in a reduction of output power at conventional output stages. Using the BTL principle increases the output power.

The maximum gain of the amplifier is fixed at 40.5 dB. The DC volume control stage has a logarithmic control characteristic. Therefore, the total gain can be controlled from 40.5 dB to -33 dB. If the DC volume control voltage falls below 0.4 V, the device will switch to the mute mode.

The amplifier is short-circuit proof to ground, V_P and across the load. Also a thermal protection circuit is implemented. If the crystal temperature rises above +150 °C the gain will be reduced, thereby reducing the output power. Special attention is given to switch-on and switch-off clicks, low HF radiation and a good overall stability.

Power dissipation

Assume V_P = 12 V; R_L = 16 Ω . The maximum sine wave dissipation is = 1.8 W.

The R_{th vj-a} of the package is 55 K/W. Therefore $T_{amb\ (max)} = 150 - 55 \times 1.8 = 51 \,^{\circ}C$.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _P	supply voltage		_	18	٧
V _{3, 5}	input voltage pins 3 and 5		_	5	٧
I _{ORM}	repetitive peak output current		_	1.25	Α
I _{OSM}	non-repetitive peak output current		_	1.5	Α
P _{tot}	total power dissipation	T _{case} < 60 °C	_	9	W
T _{amb}	operating ambient temperature		-40	+85	°C
T _{stg}	storage temperature		-55	+150	°C
T _{vj}	virtual junction temperature		_	+150	°C
T _{sc}	short-circuit time		_	1	h

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient in free air	55	K/W	
R _{th j-c}	thermal resistance from junction to case	10	K/W	

5 W mono BTL audio amplifier with DC volume control

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CHARACTERISTICS

 $V_P = 12 \text{ V}$; $V_{DC} = 1.4 \text{ V}$; f = 1 kHz; $R_L = 16 \Omega$; $T_{amb} = 25 \degree C$; unless otherwise specified (see Fig.13).

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT	
Supply						
V _P	positive supply voltage		4.5	_	18	V
I _{q(tot)}	total quiescent current	note 1; $R_L = \infty$	_	9.2	13	mA
Maximum	gain (V ₅ = 1.4 V)					
Po	output power	THD = 10%; $R_L = 16 \Omega$	3	3.5	_	W
		THD = 10%; $R_L = 8 \Omega$	5	5.5	_	W
THD	total harmonic distortion	$P_{O} = 0.5 \text{ W}$	_	0.3	1	%
G _{v(max)}	maximum total voltage gain		39.5	40.5	41.5	dB
VI	input signal handling (RMS value)	$G_{v(max)} = 0 dB; THD < 1\%$	1.0	_	_	V
V _{no}	noise output voltage (RMS value)	note 2; f = 500 kHz	_	210	_	μV
В	bandwidth	at -1 dB	_	0.02 to 300		kHz
SVRR	supply voltage ripple rejection	note 3	34	38	_	dB
$ \Delta V_{O} $	DC output offset voltage	$ V_8-v_6 $	_	0	200	mV
Z _I	input impedance (pin 3)		15	20	25	kΩ
Mute posi	tion					
Vo	output voltage in mute position	note 4; $V_5 \le 0.4 \text{ V}$; $V_1 = 1.0 \text{ V}$	_	35	45	μV
DC volum	e control; note 5					
ф	gain control		68	73.5	_	dB
I ₅	control current	V ₅ = 0 V	-20	-25	-30	μΑ

Notes

- 1. With a load connected to the outputs the quiescent current will increase, the maximum value of this increase being equal to the DC output offset voltage divided by R_L .
- 2. The noise output voltage (RMS value) at f = 500 kHz is measured with R_S = 0 Ω and B = 5 kHz.
- 3. The ripple rejection is measured with $R_S = 0 \Omega$ and f = 100 Hz to 10 kHz. The ripple voltage V_R of 200 mV (RMS value) is applied to the positive supply rail.
- 4. The noise output voltage (RMS value) is measured with R_S = 5 k Ω unweighted.
- 5. The DC volume control can be configured in several ways. Two possible circuits are shown in Figs 14 and 15. The circuits at the volume control pin will influence the switch-on and switch-off behaviour and the maximum voltage gain.

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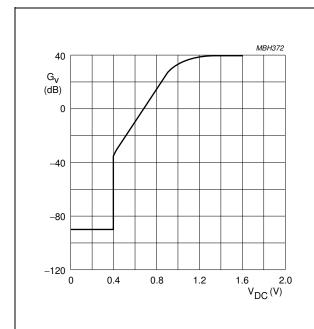
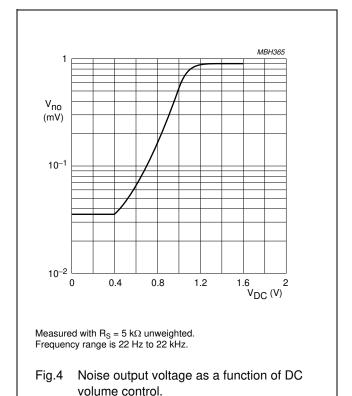


Fig.3 Gain control as a function of DC volume control.



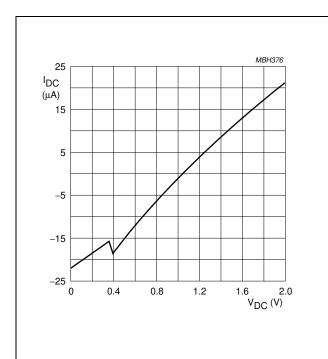
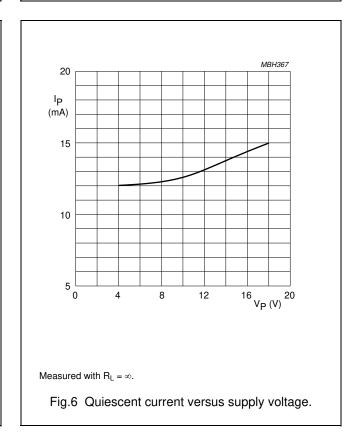
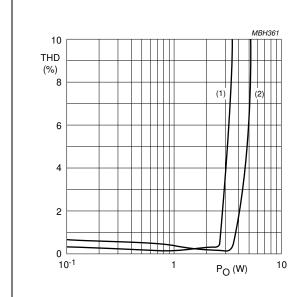


Fig.5 Control current as a function of DC volume control.



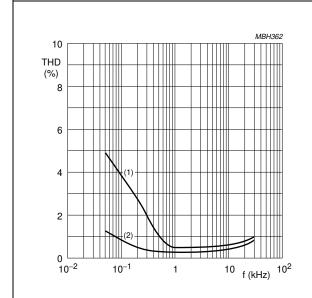
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- (1) R_L 16 Ω .
- (2) $R_L = 8 \Omega$.

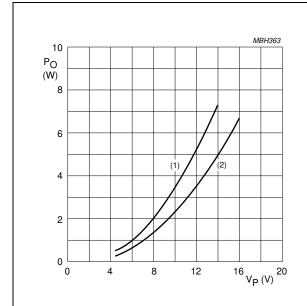
Fig.7 Total harmonic distortion versus output power.



 $P_{O} = 0.1 W.$

- (1) $G_{v(max)} = 40 \text{ dB}.$
- (2) $G_{v(max)} = 30 \text{ dB}.$

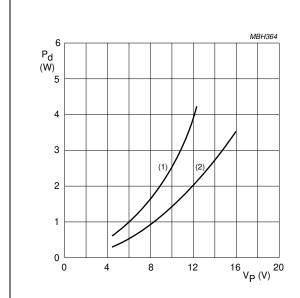
Fig.8 Total harmonic distortion versus frequency.



Measured at a THD of 10%. The maximum output power is limited by the maximum power dissipation and the maximum available output current.

- (1) $R_L = 8 \Omega$.
- (2) $R_L = 16 \Omega$.

Fig.9 Output power versus supply voltage.

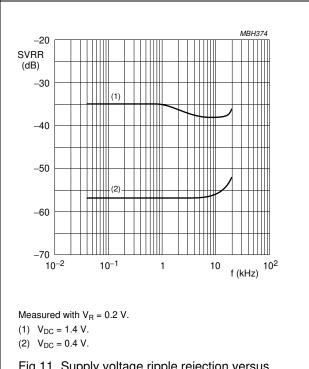


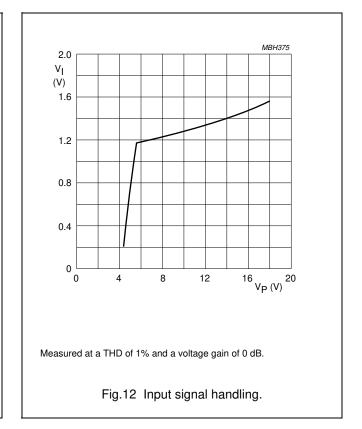
- (1) $R_L = 8 \Omega$.
- (2) $R_L = 16 \ \Omega$.

Fig.10 Total worst case power dissipation versus supply voltage.

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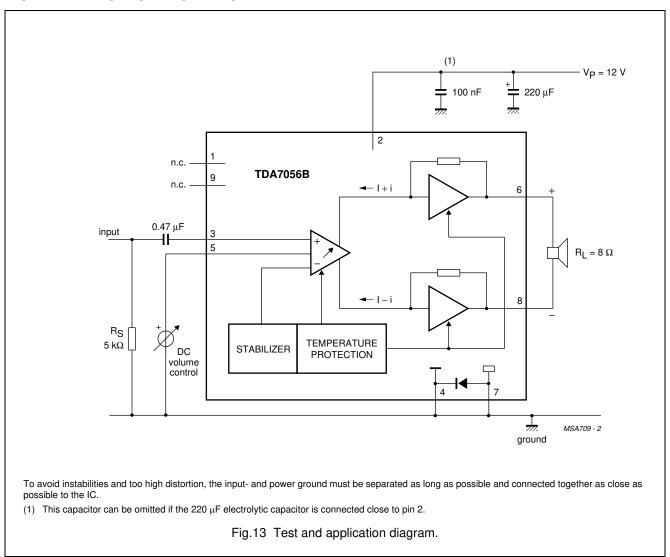




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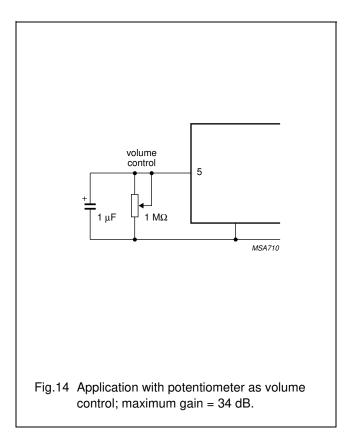
TEST AND APPLICATION INFORMATION

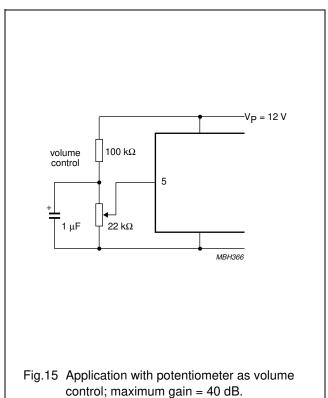


For single-end application the output peak current may not exceed 100 mA; at higher output currents the short circuit protection (MLC) will be activated.

5 W mono BTL audio amplifier with DC volume control

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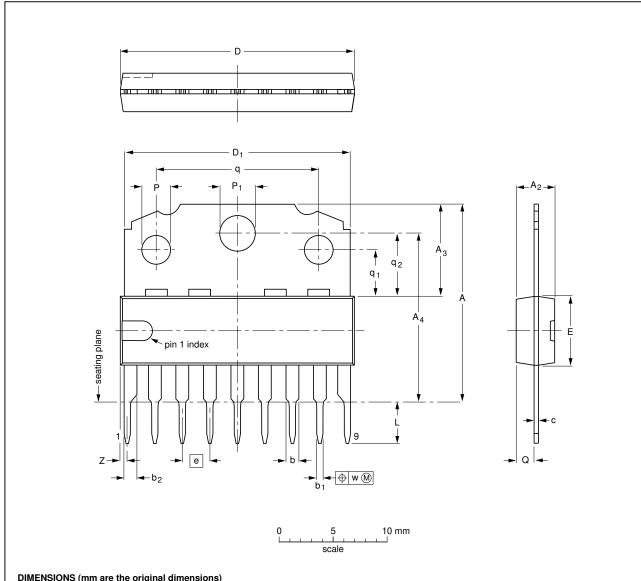
5 W mono BTL audio amplifier with DC volume control

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PACKAGE OUTLINE

SIL9MPF: plastic single in-line medium power package with fin; 9 leads

SOT110-1



DIMENSIONS (mm are the original dimensions)

							,														
UNIT	Α	A ₂ max.	A ₃	A 4	b	b ₁	b ₂	С	D ⁽¹⁾	D ₁	E ⁽¹⁾	е	L	P	P ₁	Q	q	q ₁	q ₂	w	Z ⁽¹⁾ max.
mm	18.5 17.8	3.7	8.7 8.0	15.8 15.4	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	3.9 3.4	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.25	1

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC JE	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT110-1						95-02-25 03-03-12	

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 $^{\circ}$ C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 $^{\circ}$ C, contact may be up to 5 seconds.

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com

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